

# Short Course on Semiconductor Packaging with Hands-on Training

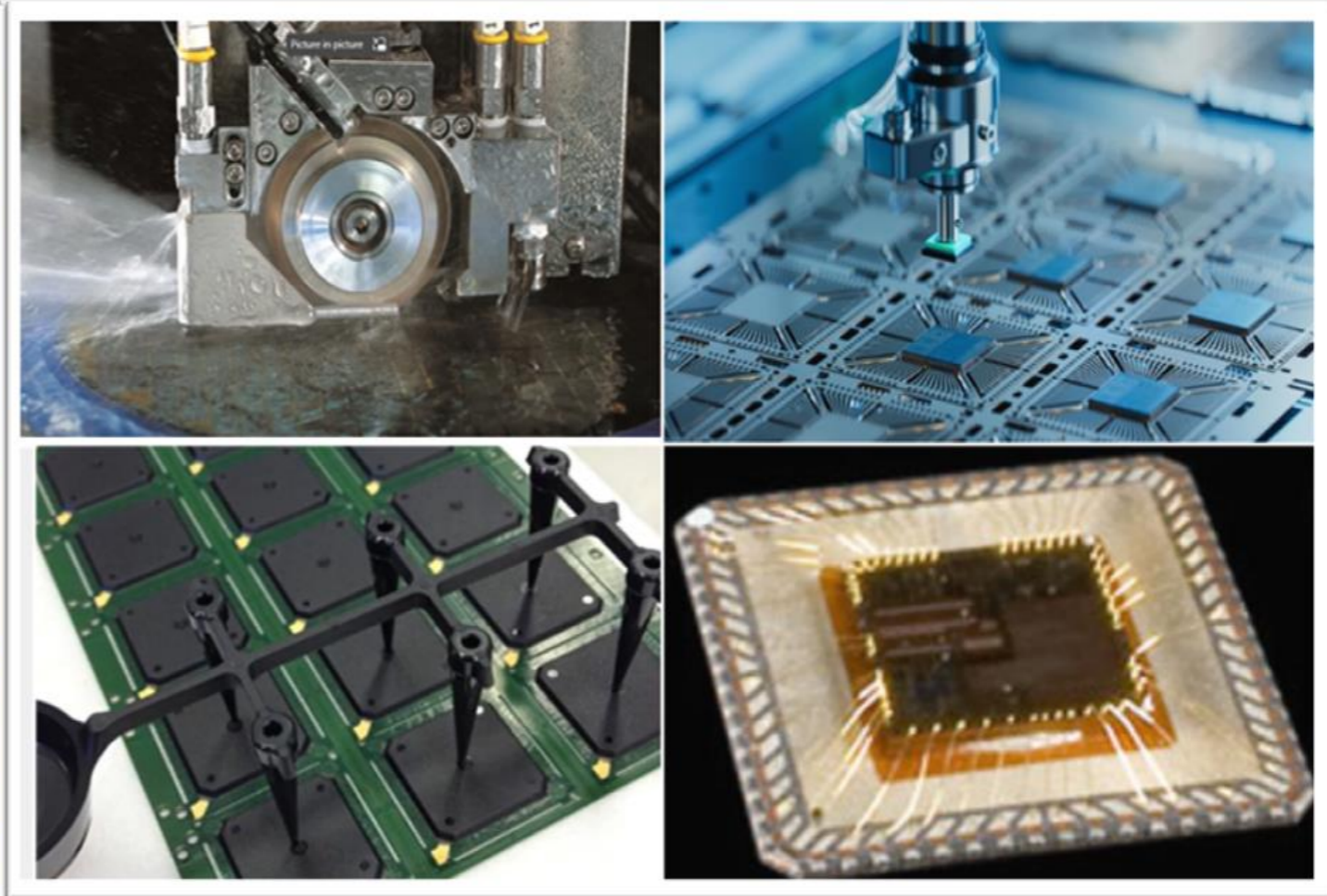


Centre for Semiconductor Technologies (SEMIX)

## Semiconductor Fabrication



## Semiconductor Packaging



### Course Co-ordinator

Prof. Veeresh Deshpande

Department of Electrical Engineering  
IIT Bombay,

Powai, Mumbai – 400 076

**16<sup>th</sup> November to 20<sup>th</sup> November 2023**

Course conducted by:

*The Centre for Semiconductor Technologies (SemiX),  
Indian Institute of Technology Bombay (IITB)*

*In association with: **Kaynes SemiCon***

*Job role networking session with **Kaynes SemiCon***



## Introduction

India is poised to grow its local semiconductor industry. The government of India has brought out India Semiconductor Mission (ISM) to coordinate the efforts and set in place policy for growing the semiconductor ecosystem. Several private companies are setting up manufacturing units on chip packaging and testing (ATMP/OSAT). As this is an emerging area, there is a skill gap at various levels (from PhD to technicians) in the workforce in India. Particularly, the skill gap at engineer and technician level (diploma/vocational training education level) needs to be bridged at the earliest, as the required workforce at this level will be the largest. The semiconductor chip packaging domain needs to training and education options as this is the least developed in India.

## Course Content

Introduction to semiconductor technology and manufacturing  
Cleanroom environment and fundamentals  
Semiconductor packaging: basic to advanced packaging technologies  
Various unit process modules involved in semiconductor packaging  
Discussion and test on course content  
Single chip packaging eyes-on and hands-on training

**Highlight: Interaction for job opportunities at Kaynes SemiCon**

## Accommodation

Limited accommodation is available on a first-come-first-serve basis (self-payment) in Hostels, IIT Bombay  
– Rs 300 per person per day on sharing basis (Room rent + Mattress Charges) - Payment to be made in advance  
[cepsemix@ee.iitb.ac.in](mailto:cepsemix@ee.iitb.ac.in)

## Broad Objectives

The broad objectives of this course are as follows:

- To provide an overview of semiconductor packaging technologies in manufacturing
- To provide necessary fundamental theory and develop understanding of processes involved in packaging
- To provide **lab scale hands-on training on single chip packaging process** steps with aim to make students quickly ramp-up in packaging job roles
- To provide interaction and **networking for students with Kaynes SemiCon for job opportunities** in their upcoming OSAT fab.

## Faculty

Renowned faculty members from IIT Bombay will deliver lectures along with industry professionals from Kaynes SemiCon. Lab sessions will be led by experienced research staff from IITBNF and Labs in Mechanical Engineering Department

## Venue for Lectures and Labs

- Lectures - Victor Menezes Convention Centre (VMCC), IIT Bombay
- Lab sessions – IIT Bombay Nanofabrication Facility (IITBNF), Electrical Engineering Department, IIT Bombay
- Labs in the Mechanical Engineering Department

## Who may benefit?

- **Students (graduated or about to graduate) looking for career in semi-packaging**
- Startups, Scientists, and Technical Staff
- Government Officials

## Lecture Notes

To fully realize the objectives of the course, the lecture notes/slides will be made available to the participants after the event

## Registration

Per participant

Rs 80,000 /- for industry participants

Rs 40,000 /- for faculty from academia

Rs 75,000 /- for government officials

Rs 25,000/- for students

Rs 25,000/- for startup engineers

The course fee includes course material, lunch, and coffee/tea

## Important Dates

Last date for receipt of the registration form:  
12<sup>th</sup> November 2023

Course dates: 16<sup>th</sup> Nov. to 20<sup>th</sup> Nov., 2023

## Contact

For any further queries, please contact us at [office.semix@iitb.ac.in](mailto:office.semix@iitb.ac.in) or 022-21593930

*\* Minimum educational requirement is a Diploma or Bachelor's Degree in Science/Engineering*